

Abstract

A polymer masking flux for fabricating external contacts on semiconductor components includes a polymer resin, a fluxing agent and a curing agent. The flux is configured to clean contact pads for the external contacts, and to hold the external contacts on the contact pads during a reflow bonding process. The flux is also configured to cure or polymerize, to form donut shaped polymer support members for the external contacts. In addition, the flux is configured to mask conductive traces in electrical communication with the contact pads, and to electrically insulate the external contacts from the conductive traces. The external contacts can be pre-formed solder balls, or deposited solder bumps. In the case of solder bumps, the flux can include solder particles configured to coalesce into the solder bumps.

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